

Title (en)
SINTERED POLYCRYSTALLINE DIAMOND MATERIAL WITH EXTREMELY FINE MICROSTRUCTURES

Title (de)
GESINTERTES POLYKRISTALLINES DIAMANTMATERIAL MIT EXTREM FEINEN MIKROSTRUKTUREN

Title (fr)
DIAMANT POLYCRISTALLIN FRITTE A MICROSTRUCTURES EXTREMEMENT FINES

Publication
EP 1931594 A4 20130102 (EN)

Application
EP 06803564 A 20060914

Priority
• US 2006035801 W 20060914
• US 71722705 P 20050915
• US 53138906 A 20060913

Abstract (en)
[origin: US2007056778A1] A sintered polycrystalline diamond material (PCD) of extremely fine grain size is manufactured by sintering a diamond powder with pre-blended catalyst metal under high pressure/high temperature (HP/HT) processing. The PCD material has an average sintered diamond grain structure of less than 1.0 mum.

IPC 8 full level
C04B 35/52 (2006.01); **B01J 3/06** (2006.01); **B22F 7/06** (2006.01); **C22C 26/00** (2006.01)

CPC (source: EP KR US)
B01J 3/062 (2013.01 - EP US); **B22F 7/062** (2013.01 - EP US); **C04B 35/52** (2013.01 - EP KR US); **C22C 26/00** (2013.01 - EP US); **B01J 2203/062** (2013.01 - EP US); **B01J 2203/0655** (2013.01 - EP US); **B01J 2203/0685** (2013.01 - EP US); **B22F 2005/002** (2013.01 - EP US); **B22F 2998/00** (2013.01 - EP US); **C04B 2235/427** (2013.01 - EP KR US); **C04B 2235/5445** (2013.01 - KR); **C04B 2235/722** (2013.01 - EP US); **C04B 2235/723** (2013.01 - EP US); **C04B 2235/782** (2013.01 - EP US); **C04B 2235/785** (2013.01 - EP US); **C04B 2235/95** (2013.01 - EP US); **E21B 10/46** (2013.01 - KR)

Citation (search report)
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• [XA] US 2005019114 A1 20050127 - SUNG CHIEN-MIN [TW]
• [XA] WO 2004054943 A1 20040701 - JAPAN SCIENCE & TECH AGENCY [JP], et al
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Designated contracting state (EPC)
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